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COMMISSION ON SPECTROCHEMICAL AND OTHER OPTICAL PROCEDURES FOR ANALYSIS

NOMENCLATURE, SYMBOLS, UNITS, AND THEIR USAGE IN SPECTROCHEMICAL ANALYSIS :

CUMULATIVE INDEX OF TERMS: PARTS I — XIII

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A series of documents dealing with nomenclature, symbols and units used in spectrochemical analysis has been issued by IUPAC to date in thirteen parts:

Part I. General Atomic Emission Spectroscopy [Pure Appl. Chem., 30, 653-679 (1972)].

Part II. Data Interpretation [Pure Appl. Chem., 45, 99-103 (1976)].

Part III. Analytical Flame Spectroscopy and Associated Non-Flame Procedures [Pure Appl. Chem. 45, 105-123 (1976)].

Part IV. X-ray Emission Spectroscopy [Pure Appl. Chem. 52, 2541-2552 (1980)].

Part V. Radiation Sources [Pure Appl. Chem. 57, 1453-1490 (1985)].

Part VI. Molecular Luminescence Spectroscopy [Pure Appl. Chem. 56, 231-345 (1984)].

Part VII. Molecular Absorption Spectroscopy, Ultraviolet and Visible (UV/VIS) [Pure Appl. Chem. 60, 1449-1460 (1988)].

Part VIII. Nomenclature System for X-ray Spectroscopy [Pure Appl. Chem. 63, 735-746 (1991)].

Part IX. Instrumentation for the Spectral Dispersion and Isolation of Optical Radiation [Pure Appl. Chem. 67, 1725-1744, (1995)] .

Part X. Preparation of Materials for Analytical Atomic Spectroscopy and other Related Techniques [Pure Appl. Chem. 60, 1461-1472 (1988)].

Part XI. Radiation Detectors [Pure Appl. Chem. 67, 1745-1760 (1995)].

Part XII. Terms Related to Electrothermal Atomization [Pure Appl. Chem. 64, 253-259 (1992)].

Part XIII. Terms Related to Chemical Vapour Generation [Pure Appl. Chem. 64, 261-264 (1992)].

Nomenclature, Symbols, Units, and their Usage in Spectrochemical Analysis : Cumulative Index of Terms: Parts I — XIII

The references in this Index of Terms are given as follows:

Roman numeral = Part
First arabic = Section
Second, third arabic = Paragraph

A			
abnormal glow discharge	V 7.2.2	analysis element	I 6.1; 6.3.1
absolute radiometers	XI 5	analyte	III 4.1
absolute temperature	III 6.1; Table 2.1	(analyte) addition technique	III 4.2; 4.4.3
absorbance, <i>A</i>	VII 2.2; I Table App.	(analyte) signal	III 4.1
absorbance matching	VII 4.7	analytical addition technique	V 5.4
absorbance profile	XII 2.2.3	analytical blank	X 2.3.1
absorbing solution	XIII 1.2	analytical calibration curves	II 3.1; VII 4.2
absorptance	VII 2.2	analytical calibration functions	II 3.1; VII 4.2
absorption	V 2.3.5	analytical concentration range	V 5.4
absorption band	VII 2.1	analytical curve	I 6.3.2; II 3.1; III 4.1
absorption cell	XIII 1.3	analytical-curve technique	III 4.2; V 5.4
absorption continuum	VIII 2.4	analytical-curves	IV 6.3
absorption edge	VIII 2.4	analytical electrode	V 3.4.1
absorption edge jump, <i>j</i>	IV 4.3.2	analytical evaluation curves	II 3.1
absorption edge wavelength	IV 4.3	analytical evaluation functions	II 3.1
absorption factor	I 5.3.1; VII 2.2	analytical function	II 3.1
absorption filters	IX 5.2	analytical functions	IV 6.4
absorption limit	VIII 2.4	analytical gap	V 3.4.1
absorption path length	VII 3.2.1	analytical gap	V 4
absorption profile	V 2.4.5	analytical result	III 4.1
absorptivity, α	I Table App.	analytical sample	X 2.3.1
absorptivity, molar, ϵ	I Table App.	Anger camera	XI 8.1.7
accuracy	II 2.7; III 4.3.2	angle of diffraction	IX 4.2.2
acid/base interaction	VI 2.2.4	angle of divergence	V 6
acid-digestion	X 3.2.1	angle of incidence	IX 4.2.2
acid vapour-phase attack	X 3.2.1	Angstrom, Å	I Table App.
acoustical shock-wave sifter		angular dispersion	I 5.2.3; IV 5.1.2; IX 4.2
system	V 3.4.3	angular nebulizer	III 3.1.1.2
acousto-optical shutter	V 6.2.3	anion effect	III 4.4.2.2
activated carbon	X 3.3	annealing	X 2.1.2
activation energy of atomization	XII 2.2.3	annular anode	V 7.2.2
active junction	XI 5.1	anode dark space	V 7.1.1
active medium	V 6.1	anode glow	V 7.1.1
additive	III 4.1	anodic oxidation	X 3.2.7
additives	I 7.7.1	anodic vaporization	V 3.4.1
additive double monochromator	IX 2.1.1	anti-Stokes fluorescence	III 5.1.3
aerosol	III 3.1.1.1; V 3.4.2;	anti-Stokes type	VI 2.2.3
	XII 2.2.1	aperture stop of diameter, <i>D</i>	I 5.1.3
aerosol deposition technique	V 3.4.3	aperture width	I 5.1.3; XI 8
agglomeration	XI 4.6	apparent concentration	III 4.4.1
aging	V 3.1	appearance temperature	XII 2.2.3
alternating current	V 3.1.1	arc atmosphere	V 3.5.2
alternating current (ac) arc	V 4.1.1	arc chamber	V 3.5.2
alternating current (ac) spark	X 3.2.6	arc column	V 3.1.2
amalgamation	XIII 1.2	arc gap	V 3.4.1
amalgamator	VII 3	arc lamp	V 7.3.1
amplitude modulation		arc-like discharge	V 4.3
		arc-stand	V 3.4.1

array (one- or two-dimensional)	XI 8	Beer-Lambert-Bouguer law	VII 2.2
array geometry	XI 8	belt sander	X 2.1.2
ashing	XII 2.2.1	best precision absorbance	VII 5.1
ashing temperature	XII 2.2.1	bias	II 2.7; III 4.3.2
ashing time	XII 2.2.1	biased mode	XI 7.2.1
aspiration	III 3.1.1.1	biased oscillating discharge	V 4.1.2
astigmatic	IX 2	binary collision	V 7.1.3
Aston dark space	V 7.1.1	binder	X 3.1.2
atmospheric particulates	X 2.3.1	binning	XI 8.2.4.1
atomic bombardment	V 7	biplanar vacuum phototubes	XI 6.1.2
atomic fluorescence	III 5.1.3; V 2.3.5	bipolar transistor	XI 7.2.5
atomic line	I 7.6.1.; III 5.1.3	black-body radiation	V 2.2.3
atomic spectrum	V 2.2.1	blackening, <i>S</i>	I 8.3.6
atomization	III 3.1.1.1; V 2	blank, S_{bl}	II 2.5
atomization curve	XII 2.2.3	blank background	III 4.1
atomization stage	XII 2.2.1	blank cell	VII 3.2.1
atomization surface	XII 2.1.4	blank measure	III 4.1; VI 4.8
atomization surface temperature	XII 2.2.2	blank scatter	III 4.3.1
atomization temperature	XII 2.2.1	blank solution	III 5.1
atomization time	XII 2.2.1	blaze	IX 4.2.2
atomizer	III 3.1.1.1	blaze angle, <i>b</i>	IX 4.2.2
Auger electron	IV 4.3.1	blaze angle, <i>b</i>	I 5.1.9
Auger transition	VIII 2.1	blaze wavelength	IX 4.2.2
autocollimative	IX 2	bleachable substance	V 6.2.3
auxiliary discharge	V 6.7.1	bleed	V 7.3.2
auxiliary spark gap (tandem gap)	V 4.2	blender	X 2.3.2
avalanche photodiode	XI 7.2.4	blow-in procedure	V 3.4.3
average gas pressure	V 2	boiling temperature	V 6
averaged spectra	VII 3.3	boat	XII 2.1.4
axial electrode	V 5.2	boat atomizer	XII 2.1.2
axial wire anode	XI 6.4	bolometer	VI 3.3; XI 5.3
B		bomb-digestion	X 3.2.1
backed	X 3.1.2	boosted hollow cathode	V 7.3.3
background	I 6.3.3	boosted output glow-discharge	V 7.3.4
background, S_b	II 2.5	boosted magnetic field glow discharge	V 7.3.4
background correction technique	V 5.4	box and grid structure	XI 6.2
background corrector	III 3.5	bracketing technique	III 4.2; V 5.4
background radiation	V 2.2.4	Bragg's equation	IV 5.1.1
background suppression	V 3.6	braid atomizer	XII 2.1.2
Baker-Sampson-Seidel- transformation	I 8.3.4	breakdown jitter	V 4.2
ball-mill	X 2.3.1	breakdown potential	XI 7.2.5
band-blocking filters	IX 5.2	breakdown time	V 4.2
band-facer	X 2.1.2	breakdown tension	V 4.2
band-pass filters	IX 5.2	Bremsstrahlung	IV 4.1.3; VIII 2.1
band spectra	V 2.2.3	broadening process	V 2.4
bandwidth	I 4.2	brush discharge	V 5.2
bar samples	X 2.1.1	buffer-addition technique	III 4.4.3
base	I 6.1	buffered arc	V 3.6
base line error	VII 6.1	bulk sample	X Figure 2
baseline technique	III 4.4.3	Bunsen-burner	III 3.1 1.3
batch mode	XIII 1.1	burner	III 3.1.1.3
beam of width, <i>W</i>	I 5.1.8	burning spot	V 4.8
beam splitter	IX 5.3	burning tension	V 3
Beer's law	I Table App.	burning-off effect	V 3.4.2
		C	

CVAAS	XIII 1.1	charging current	V 4.1.1
cadmium sulfide photoconductive detector	XI 7.1	charging resistor	V 4.1.1
camera	IX 3.2	charging time constant	V 4.2
capacitive discharge	XII 2.1	charring	XII 2.2.1
capacitively coupled plasma	V 5.2	charring temperature	XII 2.2.1
capacitor tension	V 4	charring time	XII 2.2.1
capillary arc	V 3.4.4	chemical actinometer	VI 3.3
capillary electrode	V 3.4.3	chemical equilibrium	III 6.1
capillary tube	V 7.3.2	chemical etching	X 2.1.2
capsule-in-flame atomizer	XII 2.1.1	chemical flame	V 1
carbide coating	XII 2.1.3	chemical interference	III 4.4.2.2
carbon atomizer	III 3.1.3.3.1	chemical leaching	X 3.2.2
carbon-cup atomizer	III 3.1.3.3.1	chemical modifier	XII 2.3
carbon-tube furnace	III 3.1.3.3.1	chemical vapour generation	XIII 1.1
carbonyl generation	XIII 1.1	chemiluminescence	VI 2.1; Table 2.1
carrier distillation arc	V 3.6	chemiluminescence analysis	VI 4.8
carrier electrode	V 3.4.2	chevron orientation	XI 8.1.6
carrier gas	III 3.2; XIII 1.3	chill-pin samples	X 2.1.1
cast samples	X 2.1.1	chips	X 2.1.2
cast-pin samples	X 2.1.1	chopper	III 3.3
cataphoresis	V 2.1	Christiansen filter	IX 5.2
cathode dark space (Crookes Hittorf dark space)	V 7.1.1	circular cage structure	XI 6.2
cathode fall tension	V 3	circular polarization	V 2.5 1
cathode fall region	V 7.1.2	clean glove box	X 2 3 1
cathode glow	V 7.1.1	clean-room	X 2.3 1
cathode layer arc	V 3.4.1	clean-up	V 7.1.4
cathodic sputtering	III 3.1.3.3.2; 3.2; V 7	cleaning temperature	XII 2.2.1
cathodic vaporization	V 3.4.1	cleaning time	XII 2.2.1
cation effect	III 4.4.2.2	closed cell	VII 3.2.2
cell error	VII 6.9	closed oxygen combustion system	X 3.1.3
cell path length	VII 3.2.1	closed system	XIII 1.3
cementation	X 3.3	coaxial cavities	V 5.3.2
centre-to-centre spacing	XI 8	coefficient of linear expansion	I 8.4.4
centrifugation	X 2.4	coherent electromagnetic radiation	V 1
chamber-type nebulizer	III 3.1.1.2	coherent radiation	V 6
channel electron multiplier (CEM)	XI 6.2.2	coherent source	V 1
channeling	V 7.1.3	cold finger	X 3.4
channel photomultiplier tube	XI 6.2.2	cold-finger cell	VII 3.2.4
characteristic concentration	III 4.2	cold hollow cathode	V 7.3.3
characteristic mass	XII 2.3	cold trap	X 3.4; XIII 1.2
characteristic mass for integrated absorption	XII 2.3	cold vapour AAS	XIII 1.1
characteristic mass for peak absorption	XII 2.3	collecting device	X 3.4
characteristic X-ray emission	VIII 2.1	collection system	XIII 1.2
characteristic X-ray production	IV 4.1.2	collection time	XIII 1.2
charge-coupled devices (CCDs)	XI 8.2.4	collector	XIII 1.2
charge exchange	V 7.1.2	collimator focal length	IX 4.1
charge-injection devices (CIDs)	XI 8.2.4	collisional broadening	V 2.4.4
charge pattern	XI 8.2.4	collisional chains	V 7.1.3
charge transfer	V 7.1.2	collisional cross-section	V 2.3.3
charge-transfer device	XI 8.2.4	collisional de-excitation	V 2 3.4
charge transfer efficiency	XI 8.2.4.1	collisional shift	V 2 4.4
charging circuits	V 4.1.1	collisions per time unit	V 2.3.3
		compensated region	XI 7.2.3
		compensating junction	XI 5.1
		complete evaporation	V 3.4.2

complex composition	2.3.2	corrected excitation spectrum	VI 4.3; Table 4.2
component	V 2.1	corrected intensity	IV 5.1.5
composite sample	X 2.3.1	corrected luminescence	VI 4.7;
compromise condition	V 5.1.3	polarization spectrum	Table 4.2
concave grating	IX 4.2.2	corrected quantum yield of fluorescence	
concave grating mountings	IX 9.2	(phosphorescence)	VI 4.6;
concentration	I 6.2; II 2.1;		Table 4.2
	III 4.1	correction plate	IX 5.3
concentration, c	I Table App.	Coster-Kronig transition	VIII 2.1
concentration index	I 6.3.2	counter electrode	V 3.4.1
concentration ratio	I 6.2.2	counting precision	IV 6.2
concentric nebulizer	III 3.1.1.2	coupling efficiency	V 5.1.1
concept of optical conductance	IX 7.3	crater	V 6.4
concomitants	I 6.1; III 4.1	crater depth	V 6.4
condensed arc	V 3.5.1	crater diameter	V 6.4
configuration	VIII 2.2	crater shape	V 6.4
confined atomizer	XII 2.1.2	critically damped discharge	V 4.1.2
confiner plate	V 4.5	cross section for ionization	IV 4.1.2
confocal configuration	V 6.1	crystal characteristics	IV 5.1.3
coning and quartering	X 2.3.1	crystal diffraction	IV 5.1.1
constant temperature arc	V 3.6	crystal lattice	V 7.1.3
constant temperature atomization	XII 2.2.2	crystal-controlled oscillator	V 5.1.1
constant tension	V 3.5.1	cup atomizer	XII 2.1.2
constituents	I 6.1	cup electrode	V 3.4.2
constricted glow discharge	V 7.2.2	cupellation	X 3.3
constriction	V 3.1.2	current density	V 3
contact noise	XI 4.3	current-carrying	V 3.1
continuous-flow cell	VII 3.2.4	current-carrying plasma	III 3.1.3.2
continuous mode	XIII 1.1	current-free (plasma)	III 3.1.3.2;
continuous radiation	V 1		V 3.1
continuous spectral background	V 4.8	current-time relationship	V 3.1
continuous-strip photomultiplier	XI 6.2.1	curve corrector	III 3.5
continuous supply	V 3.4.3	curve-of-growth	III 5.1.2
continuous wave	V 6.1	curved slits	IX 4.1
continuous X-radiation	VIII 2.1	cut-off wavelength	IX 5.2
continuum	V 2.2.3	cyanogen molecular bands	V 3.5.2
continuum source	VII 3.1;	cylinder of radius r and height h	I 8.4.4
	IX 7.3.5	cylindrical cathode	XI 6.4
control gap	V 4.1.2	cylindrical cavities	V 5.3.2
control spark gap	V 4.1.2	cylindrical shape	V 7.1
controlled ac arc	V 3.1.1	Czerny-Turner mounting	IX 9.3.3
controlled atmosphere	V 3.5.2		
controlled duration spark	V 4.1.2	D	
controlled-flow nebulizer	III 3.1.1.2	dark current, i_d	III 3.4; XI 4.1
controlled high tension spark		dark current noise	XI 4.3
generator	V 4.2	dark output	XI 4.1
convection	V 2.1	dark resistance, R_d	XI 4.1
cooled cell	VII 3.2.4	Darlington configuration	XI 7.2.6
cooled hollow cathode	III 3.1.3.3.2	data acquisition	VII 3
cooling stage	XII 2.2.1	data processing	VII 3
copper spark	V 4.9	dead time, t_D	IV 5.1.5;
core levels	VIII 2.2		XI 6.4.3
cores	X 2.3.1	dedicated laboratory-ware	X 2.3.1
corrected decay time of fluorescence		defining aperture	XI 8.1.3
(phosphorescence)	VI 4.5;	degree of anisotropy	VI 4.7
	Table 4.2	degree of depolarization	VI 4.7
corrected emission spectrum	VI 4.2; Table 4.2	degree of polarization	VI 4.7

delay time	XI 4.6	dope	V 6.2
demountable lamp	III 3.2	Doppler broadening	V 2.4.2
density-separation	X 2.4	Doppler shift	V 2.4.3
depression	III 4.4.1	double arc	V 3.6
deproteination	X 3.1.3	double-beam interferometer	IX 2.2
depth-profiles	X 2.4	double-beam spectrometer	VI 3.2
derivative spectra	VII 3.3	double-beam system	III 3.3
desolvation	III 3.1.1.1	double-(spectral) beam spectrometer	VI 3.2
detectivity, D	XI 4.4	double-(synchronous) beam spectrometer	VI 3.2
detector	XI 3	double monochromator	IX 2.1.1
detector gas	XI 6.4	double-pass monochromator	IX 2.1.1
detector homogeneity	XI 4.7.2	double wavelength spectroscopy	VII 4.5
detector input	XI 4.1	drilled electrode	V 3.4.3
detector noise	XI 4.3	drillings	X 2.1.2
detector output	XI 4.1	drop generator	III 3.1.1.2
detectors for use with crystal spectrometers	IV 5.1.5	dry aerosol	III 3.1.1.1
detector window	XI 6.1	dry-ashed	X 3.1.3
deuterium lamp	VII 3.1	dry grinding	X 2.3.1
devolatilizer	I 7.7.4; X 3.1.2	dry-mass	X 2.3.2
diagram level	VIII 2.2	drying temperature	XII 2.2.1
diagram line	VIII 2.5	drying time	XII 2.2.1
diatomic gas	V 7	drying stage	XII 2.2.1
dichroism	IX 7.5	Duane-Hunt short wavelength limit, I_{\min}	IV 4.1.3
dielectric layers	IX 5.2	dummy arrays	XI 8
difference absorption spectroscopy	VII 4.4	duty cycle	V 3.1.3
differential pumping	V 7.2.2	dye laser	V 6.3.1
diffracted spectral radiant power	IX 4.2.2	dynamic (systems)	V 7.1
diffraction grating	IX 2.1	dynode chain	XI 6.2
diffraction pattern	IX 7.2.2	dynodes	XI 6.2
diffusion	V 2.1	E	
Digicon	XI 8.3	E-type delayed fluorescence	VI 2.1
diluent	I 7.7.3; X 3.1.2	Eagle mounting	IX 9.2.7
dilution test	III 4.3.2	Eagle mounting (in plane)	IX 9.2.7
direct current (dc) arc	V 2.1	Ebert mounting	IX 7.3.1
direct current (dc) spark	V 4.1.1	echelle grating	IX 4.2.2
direct-injection burner	III 3.1.1.3	echelle grating spectral apparatus	IX 9.4
direct line fluorescence	III 5.1.3	echelle monochromator	IX 9.4
direct methods	III 4.2	echelle polychromator	IX 9.4
direct transfer system	XIII 1.2	echelle spectrograph	IX 9.4
disc electrode	V 3.4.3	echelle spectrometer	IX 9.4
disc-facer	X 2.1.2	effect	III 4.4.2.2
disc-mill	X 2.3.1	effective base length	IX 4.2.1
discharge	V 7.1.2	effective diameter for a non-circular aperture stop, D_{eff}	I 5.1.3
discharge atmosphere	V 4.1.2	effective optical conductance	IX 7.3.3
discharge circuit	V 4.1.2	effective sensitive area	XI 4.7.2
discharge current	V 4	effective sensitive volume	XI 4.7.2
discharge impedance	V 4.1.2	effective spectral optical conductance of a monochromator	IX 7.3.5
dispersion, dz/dI	I 5.2.3	effective spectral width	IX 7.1.1
dispersion of a material	I 5.2.3	efficiency of atomization	III 3.1.2
dispersive component	IX 2.1	efficiency of fluorescence	III 5.1.3; Table 5.1
dissociation	III 6.1; V 2.1	efficiency of nebulization	III 3.1.2
dissociation interference	III 4.4.2.2		
distillation	V 2.1; X 3.2.6		
distribution	IV 5.1.5		
dividers	X 2.3.1		
documentation	X 2.3.1		

efficiency of the grating	IX 4.2.2	enclosed atomizer	XII 2.1.1	
Eigen-frequency	V 6.1	end-on	V 7.3.2	
ejection energy	V 7.1.2	energy dispersion	IV 5.2	
elastic collision	V 2.3.4	energy dispersive detectors	XI 3	
elastic scattering	V 2.5.2	energy levels	V 2.2.1	
electric dipole selection rules	VIII 2.3	energy resolution	XI 3	
electric quadrupole		energy resolving power	XI 3	
selection rules	VIII 2.3	energy transfer	V 2.3.4	
electrical arc	V 3	energy yield of fluorescence		
electrical discharge	V 4	(phosphorescence)	VI 4.6;	
electrical excitation	V 6.1		Table 4.1	
electrical flame-like plasma	III 3.1.3.2	enhanced phosphorescence		
electrical measuring system	III 3.5	analysis	VI 2.2.2	
electrical source parameter	V 3.5.1	enhancement	III 4.4.1;	IV
electrical spark	V 4		4.3.4	
electrically heated silica tube		entrance aperture	IX 2	
furnace	XIII 1.3	entrance aperture stop	IX 4.1	
electrode gap	V 3	entrance collimator	IX 4.1	
electrodeless discharge	V 5.3.2	entrance field stop	IX 4.1	
electrodeless discharge lamp	III 3.2	entrance pupil	IX 4.1	
electrodeless plasma	III 3.1.3.2	entrance slit	IX 2.1.1	
electro-erosion	V 3.4.4	entrance spectral slit width	IX 7.1.3	
electrolytic etching	X 2.1.2	environmental contamination	X 2.3.1	
electromagnetic coupling	V 5.1.1	enzymatic decomposition	X 3.2.4	
electromagnetic radiation	V 1	enzymatic degradation	X 3.2.4	
electron binding energy	VIII 2.2	equidistant (series of spikes)	V 6.2.3	
electron gun	XI 8.2.2	erosion technique	V 3.4.4	
electron multiplication	V 7.1.2; XI 6.2	escape peak	XI 6.4;	XI
electron pressure	V 4.8		6.2.3	
electron relaxation	VIII 2.2	ETA	XII 1	
electron shake-off	VIII 2.2	ETAAS	XII 1.1	
electron shake-up	VIII 2.2	etalon plate interferometer	IX 4.2.3	
electron temperature	V 2.3.2	ETV	XII 1.1	
electronic energy transfer	VI 2.2.2	evaporation	V 2.1	
electronic-excitation temperature	V 2.3.2	evaporation equilibrium	V 4.9	
electronic transitions	V 2.2.2	excess low-frequency noise	XI 4.3	
electronically ignited ac arc	V 3.1.1	excimer luminescence	VI 2.2.2	
electro-optical shutter	V 6.2.3	exciplex luminescence	VI 2.2.2	
electrothermal AAS	XII 1.1	excitation	III 6.1; V 2	
electrothermal atomic		excitation-emission spectrum	VI 4.4	
absorption spectrometry	XII 1.1	excitation interference	III 4.4.2.2	
electrothermal atomic		excitation level	VIII 2.2	
fluorescence spectrometry	XII 1.1	excitation monochromator	VI 3.2	
electrothermal atomization	XII 1	excitation-potential, V_{exc}	I 7.4	
electrothermal atomizer	XII 1.1	excitation region	V 5.4	
electrothermal optical		excitation source	VI 3.1	
emission spectrometry	XII 1.1	excitation spectrum	VI 4.3; VII 1	
electrothermal vaporizer	XII 1.1	excitation spectrometer	VI 3.2	
elemental coverage	V 5.4	excitation spectrometer	VI 3.2	
elliptical polarization	V 2.5.1	excitation temperature	V 2.3.2	
emission	III 5.1.1	excitation zone	V 5.1.2	
emission band	VIII 2.5	exciting power	V 6.1	
emission monochromator	VI 3.2	exciton	VIII 2.2	
emission profile	V 2.4.5	exit collimator	IX 4.3	
emission spectrum	VI 4.2	exit slit	IX 2.1.1	
emission spectrometer	VI 3.2	exit spectral slit width	IX 7.1.3	
emulsion calibration curve	I 8.3.2	exothermic reaction	V 1	
emulsion calibration function	I 8.3.2	exposure, H	I 6.3.1	

exposure time	I 7.6.4; IX 8.3.3	fluorescence excitation	VIII 2.1
extended X-ray absorption		fluorescence field	VIII 2.1
fine structure (EXAFS)	VIII 2.4	fluorescence yield	IV 4.3.1
external heavy-atom effect	VI 2.2.4	flush	V 7.1
externally ignited spark discharge	V 4.3	flux through a monochromator	I 8.4.4
external photoelectric effect	XI 6	focal length	I 5.1.4
extrinsic conductors	XI 7	focal length, f'	I 5.1.6
F		focal plane	IX 2
fabricated samples	X 2.1.1	focal spot	V 6
Fabry-Perot-etalon		focusing lens	V 6
interferometer	IX 4.2.3	focusing mirror	V 6
Fabry-Perot interferometer	IX 4.2.3	forbidden lines	VIII 2.3
faced	X 2.1.2	forced flow	XII 2.1.2
fall time, t_f	XI 4.6	foreign-gas	V 2.4.4
false lines	IX 7.6	forged samples	X 2.1.1
FANES	XII 2.1.1	forging	X 2.1.2
far scatter	IX 7.6.4	Fourier spectrometer	IX 3.3.3
Faraday dark space	V 7.1.1	fraction atomized	III 3.1.2
Faraday effect	V 6.2.3	fraction desolvated	III 3.1.2
Fastie-Ebert mounting	IX 9.3.2	fraction volatilized	III 3.1.2
fatigue effect	XI 4.6	fractional distillation	V 3.4.2; X
Fermi level	VIII 2.2	frame-transfer CCD	XI 8.2.4.1
ferroelectricity	XI 5.4	free electron	V 7.1.3
fibre optics	XI 8.1.7	free-bound transition	V 2.2.3
fibre optic face plate	XI 8.2.3	free-burning arc	V 3.1
field effect transistor (FET)	XI 7.2.7	free-burning transition	V 2.2.3
filament atomizer	XII 2.1.2	free-running operation	V 6.2.2
filings	X 2.1.2	free-running oscillator	V 5.1.1
fill-gas	III 3.2	freeze-dried	X 2.3.2
filter	III 3.3	frequency, ν	I Table App.
filter spectrometer	IX 3.3.5	frequency bandwidth, Δf	XI 4.4
fire assay	X 3.3	frequency doubling	I 9.1
first Rayleigh criterion	IX 7.2.2	frequency multiplexing	IX 3.3.3
first (second ...) derivative		frequency multiplication	V 5.1.1
absorption spectrum	VII 4.6	frozen material	X 2.3.2
first (second ...) low temperature derivative		fuel	III 3.1.1.3
absorption spectrum	VII 4.6	fuel-rich flame	III 3.1.1.3
fixed frequency of oscillation	V 5.1.1	full-frame CCD	XI 8.2.4.1
flame	III 1	full width at half	
flame background	III 4.1	maximum (FWHM)	V 2.4; IX 7.1
flame-geometry interference	III 4.4.2.2	full width at half maximum (FWHM)	
flame heated silica tube furnace	XIII 1.4	of the spectral line	IX 8.1
flame-in-tube atomizer	XIII 1.4	full width at hundredth-maximum	IX 7.1
flash-back	III 3.1.1.3	fundamental-parameter equations	IV 6.5
flash fluorimetry		furnace	XII 1.1
(phosphorimetry)	VI 4.5	furnace atomic non-thermal	
flash lamp	VI 3.1	excitation spectrometry	XII 2.1.1
flat field grating	IX 9.2.4	furnace atomizer	XII 2.1
flat field mounting	IX 9.2.4	furnace-pyrolysis	X Comments
flicker noise	XI 4.3		by experts
floating frequency	V 5.1.1	fused sample	X 3
flow-through detector	XI 6.4	fusing mixture	X
fluorescence	III 5.1.3; VI	fusing reagent	X 3.1.4
	2.1; Table 2.1	fusion (isoformation)	V 4.9
fluorescence analysis	VI 4.8	G	
fluorescence error	VII 6.8	gain	XI 6.2
		gap resistor	V 4.2

gas amplification	XI 6.4	high current arc	V 3
gas-filled X-ray detectors	XI 6.4	high frequency proportional noise	XI 4.3
gas-filled phototube	XI 6.3	high frequency shorting capacitor	V 3.5.1
gas gain	IV 5.1.5		
gas-proportional detectors	IV 5.1.5	high frequency step-up transformer (Tesla coil)	V 4.3
gas temperature	V 2.3.2; 2.2.2	high intensity hollow cathode	V 7.3.3
		high-pass filter	IX 5.2
gaseous discharge	V 1	high pressure arc lamp	V 7.3.1
gaseous form	V 7	high-pressure xenon lamp	III 3.2
gas-restricting orifice	V 7.1	high repetition rate prespark	V 4.9
gas-stabilized arc	V 3.1.2	high repetition rate spark	V 4.1.2
gated photodetector	VI 3.3	high tension spark	V 4.2
Gaussian shape	V 2.4.2	hollow-cathode discharge	III 3.1.3.3.2
Geiger counter	XI 4.3	hollow-cathode lamp	III 3.2
Geissler lamp	V 7.3.2	hollow cathode source	V 7.3.3
generation-recombination noise	XI 4.3	homogeneous filter	IX 5.2
geometrical conductance	IX 7.3.1	homogeneous magnetic field	V 3.1.2
gettering	V 7.1.4	homogeneous sample	V 6.8.3
ghosts	IX 7.6	homologous lines	I 6.3.1
giant pulse	V 6.2.3	horizontal electrode	V 3.4.3
glassy carbon	XII 2.1.3	host material	V 6.2
glassy carbon tube	XII 2.1.3	hot hollow cathode	III 3.1.3.3.2; V 7.3.3
globule arc	V 3.4.2		
glow discharge	V 7.1	hydride generation AAS	XIII 1.1
Golay cell	XI 5.5.1	hydride generator	XIII 1.1
graphite	XII 2.1.3	hydrogen diffusion flame	XIII 1.4
graphite-cup atomizer	III 3.1.3.3.1	hypersatellites	VIII 2.5
graphite platform atomization	XII 2.1.4	hysteresis	XI 4.6
graphite probe atomization	XII 2.1.4		
graphite-rod furnace	III 3.1.3.3.1	I	
graphite rod-in-flame atomizer	XII 2.1.1	ignited ac arc	V 3.5.1
graphite spark	V 4.9	ignition	V 3.1.1
graphite tube atomizer	XII 2.1.2	ignition circuit	V 4.3
graphite-tube furnace	III 3.1.3.3.1	ignition pulse	V 4.3
grating constant	IX 4.2.2	ignition spark	V 3.1.1
grating function (formula)	IX 4.2.2	ignitor circuit	V 3.5.1
grating normal	IX 4.2.2	image arrays	XI 8.2.4.1
grating width	IX 4.2.2	image converter	I 9.2
gravity-fed nebulizer	III 3.1.1.2	image device	I 3.3
gravity-fed powder sifter system	V 3.4.3	image dissection tube	XI 8.1.3
grazing incident mounting	IX 7.2.8	image intensifier	XI 9.2
grooves	IX 4.2.2	impedance converter	V 5.1.1
ground state	V 2.3.5	impedance matching	V 5.1.1
		incandescent body	V 1
H		incandescent radiation	V 2.2.3
Hadamard spectrometer	X 3.3.4	incident power	V 5.1.1
haemolysis	X 3.1.3	incident radiation	XI 3
halogen generation	XIII 1.1	incident spectral radiant power	IX 4.2.2
hammering	X 2.1.2	incoherent radiation pulse	V 6.2.2
hammer-mill	X 2.3.1	indirect methods	III 4.2
head-on tube	XI 6.1	individual particle analysis	X 2.4
heat treatment	X 2.1.2	induction coil	V 5.1
height, h	I 5.1.2	inductively coupled plasma (ICP)	III 3.1.3.2; V 5.1
height, D_h	I 5.1.3		
height of sensing area	XI 8	inductively heated atomizer	XII 1.1
heterochromatic	IX 7.1.2	inductor	V 3.5.1
HGAAS	XIII 1.1	inelastic collision	V 2.3.4
high absorber	X 3.1.2		

inert discharge atmosphere	V 4.1.2		intrinsic conductors	XI 7
inert gas-hydrogen diffusion			ion	V 2.1
flame	XIII 1.4		ion-implantation	X 2.1.2
infrared region	I Table App.		ionic bombardment	V 7
ingots	X 2.1.1		ionic line	I 7.6.1; III
inhomogeneity error	VII 5.3			5.1.1;
initial current	V 4		ionic path length	V 7.2.2
injector	V 5.1.2		ionic spectrum	V 3.6
inlet	XIII 1.3		ionization	III 6.1; V 2
inner flow	V 5.1.2; XII		ionization buffer	III 4.4.3
	2.1.2		ionization chamber	XI 6.4
inner zone	III 3.1.1.3		ionization coefficient	V 7.1.2
in-plane Eagle mounting	IX 7.2.7		ionization energy, E_i	I 7.4
in situ microanalysis	V 6.8.1		ionization interference	III 4.4.2.2
instantaneous measurement	V 5.4		ionization needle	V 4.2
instantaneous spatially			ionization potential	V 3
resolving detector	XI 8		ionization temperature	V 2.3.2
instrument function	IX 7.1.1		irradiance	IX 8.3.2; XI 2
instrumental profile	IX 7.1.1		irradiance at the exit	IX 8.3.2
instrumental samples (not			irregular radiation pulse	V 6.2.2
a recommended term)	X		isoformation	V 4.9
integral reflection coefficient	IV 5.1.3		isotopic analysis	V 7.3.3
integrated absorbance	XII 2.3			
intensified solid-state array	XI 8.3		J	
intensity	I 6.3.1		Johnson noise	XI 4.3
intensity bridge	I 8.4.4		Jones matrix	IX 7.5
intensity bridge ratio	I 8.4.4			
intensity calibrating device	I 8.4.1		K	
intensity modulated beam	VI 3.4		K series	IV 1.3
intensity modulated			Kerr cell (quadratic	
hollow cathode lamps	V 7.3.3		electro-optical effect)	V 6.2.3
intensity of a spectral line	I 6.3			
intensity versus time curve	I 7.6.4		L	
intensity-time curve	I 7.6.4; V 4.9		L-series lines	IV 1.3
interaction time	V 4.8		laboratory micro-sample	X
interchannel cross talk	XI 8.1.1		laboratory sample	X 2.3.1
interconal zone	III 3.1.1.3		lag (of a vidicon)	XI 8.2.2
inter-element effect	II 3.2; V 2.1		Lambert-Beer law	VII 2.2
interference	III 4.4.1		laminar air-flow cabinets	X 2.3.1
interference curve	III 4.4.1		laminar (flame)	III 3.1.1.3
interference filter	IX 2.2		laminar sheath	V 3.5.2
interferent	III 4.4.1		lamp	V 7
interfering lines	I 6.3.4; III		lase continuously	V 6.1
	4.4.2.1		laser	III 3.1.3.3.3;
interferometric gratings	IX 4.2.2			V 1; VI 3.1
intermediate gas	V 5.1.2		laser action	V 6.1
intermediate tube	V 5.1.2		laser-active substance	V 6.2
intermolecular transition	VI 2.2.2		laser beam	V 6.1
internal conversion	VI 2.2.2		laser erosion	V 3.4.4
internal energy	VII 2.1		laser output energy	V 6.1
internal oscillation amplitude	V 6.2.3		laser output power	V 6.1
internal photo-electric effect	XI 7		laser plume	V 6.4
internal reference line	I 6.3.1; V 5.4		laser produced vapour cloud	V 6
internal transmittance	VII 2.2		laser pulse	V 6.1
intersystem crossing	VI 2.2.2		laser resonator	V 6.1
interzonal region	III 3.1.1.3		laser shot	V 6.8.3
intra- and interchromophoric			laser source	V 6
transition	VI 2.2.2			

laser spike	V 6.2.2	lot X Figure 2	
lasing	V 6.1	low absorber	X 3.1.2
lasing threshold	V 6.2.1	low current arc	V 3
lateral diffusion interference	III 4.4.2.2	low energy collisions	IV 4.1.1
lead sulfide (PbS)		low-pass filters	IX 5.2
photoconductive detector	XI 7.1	low potential vacuum phototubes	XI 6.1.1
length of the total		low pressure arc lamp	V 7.3.1
effective prism base, <i>b</i>	I 5.1.9	low-pressure discharge lamp	III 3.2
level	VIII 2.2	low pressure electrical	
lifetime of luminescence	VI 4.5	discharge (LPED)	V 7
light modulation	III 3.3	low-pressure	
light of detection	II 4.1	mercury-discharge lamp	VII 3.1
light source	III 3.2	low temperature ashing	X 3.1.3
limit of detection	II 4.1; III 4.3.2	low temperature cell	VII 3.2.4
limited volume (of solution)	V 3.4.2	low temperature UV/VIS	
limiting stops	IX 4.1	absorption spectrum	VII 2.1
line profile function	V 2.4	lower wavelength limits	IX 4.2
line shift	V 2.4	luminescence quenching	VI 2.2.2
linear absorption coefficient	IX 4.2.1	luminescence spectrometer	VI 3; Fig. 3.1
linear attenuation coefficient, μ	IV 4.3.2	luminous	I 4.5; V 7.1.1
linear (decadic)		luminous efficacy, $K(\lambda)$	I 4.5
absorption coefficient	VII 4.2	luminous layer	V 7.1.1
linear absorbance	VII 4.2	Lyman ghosts	IX 7.6.2
linear CCD	XI 8.2.4.1		
linear decrement	V 4.1.2	M	
linear (detector)	III 3.4,	magnetic dipole selection rules	VIII 2.3
linear dispersion	I 5.2.3; IX 4.3	magnetic field glow	
linear dispersion, dI/dx	I 5.2.4	discharge source	V 7.3.4
linear electro-optical effect	V 6.2.3	magnetic separation	X 2.4
linear focused structure		magnetically stabilized arc	V 3.1.2
(of a dynode chain)	XI 6.2	magneto-optical shutter	V 6.2.3
linear photodiode array	XI 8.1.1	magnetron	V 5.3
linear photoelectric		mains supply tension	V 4.4
absorption coefficient	IV 4.3.2	major constituent	I 6.1
linear polarization	V 2.5.1	manual-separation	X 2.4
linear polarization of		many-electron interaction	VIII 2.4
luminescence	VI 4.7	mass attenuation coefficient	IV 4.3.3
linear polarizer	VI 3.5	master grating	IX 4.2.2
linear scattering coefficient	IV 4.3.2	matched cells	VII 3.2.1
linearity of responsivity	XI 4.5	material dispersion	IX 4.2.1
lines (spectral)	IX 4.2.2	matrix	I 6.1
line-to-background		matrix effect	III 4.4.2.2.
radiant power ratio	IX 8.3.1	matrix effects	I 6.1; 7.7.3;
linisher	X 2.1.2		V 2.1
liquid laser	V 6.3.1	matrix geometry	XI 8
liquid sample	V 3.4.2	maximum permissible	
liquid sample injection	V 3.4.2	beam diameter	IX 4.2.3
liquid slurries	V 5.4	maximum spectral radiance	VII 3.1
Littrow prism mounting	IX 9.1.1	maximum wavelength	IV 5.1.1
load resistor	V 3.5.1	mean wavelength	IX 7.4.2
local analysis	III 3.1.3.3.3;	measure	III 4.1
	V 6.8.1	measure of concentration	
local (gas) temperature	V 2.3.2	and quantity	II 2.1
local thermal equilibrium	V 2.3.2	measured emission spectrum	VI 4.2; Table
logarithmic decrement	V 4.1.2		4.2
long tube device	III 3.1.3.1	measured intensity	IV 5.1.5
longitudinal mode	V 6.1	measured quantum yield of fluorescence	
loop atomizer	XII 2.1.2		

(phosphorescence)	VI 4.6; Table 4.2	muffle furnace	X 3.1.3
measurement period	V 4.9	multichannel analyzer	IV 5.2.3
measuring beam	XII 2.1.2	multicomponent analysis	VII 4.2
measuring time	IX 8.3.3	multi-crystal cameras	XI 8.1.7
median wavelength	IX 7.4.4	multi-element lamp	III 3.2
medium current arc	V 3	multipass system	III 3.3
medium power	V 6.2.3	multiple-pass cell	VII 3.2.4
medium tension spark	V 4.3	multi-purpose spark source	V 4.3
medium tension spark generator	V 4.3	multislot burner	III 3.1.1.3
Méker-burner	III 3.1.1.3	multiple beam interferometer	IX 2.1
mercury-cadmium-telluride (HgCdTe)		multiple ionization	VIII 2.5
photoconductive detector	XI 7.1	multiple ionized and excited levels	VIII 2.2
mercury-vapour generator	XIII 1.1	multiple monochromator	IX 2.1.1
metal oxide semiconductor (MOS) structure	XI 8.2.4	multiplex spectrometer	IX 3.3.3
metal vapour arc lamps	V 7.3.1	multipole lines	VIII 2.3
metal vapour lamp	III 3.2	multi-wire (PSPC)	XI 8.1.5
metallic foil	XII 2.1.4	mutual interference	III 4.4.1i
metallic glasses	X 3.1.1	N	
metallurgical history	X 2.1.2	nanometer	I Table App.
metastable state	V 2.3.4	narrower spectral line	V 7.3.1
Michelson interferometer	IX 5.3	natural broadening	V 2.4.1
micro-analysis	V 6.8.2; X 2.4	natural impedance	V 4.1.2
micro-areas	X 2.4	Nd-glass	V 6.2
microchannel plate (MCP)	XI 8.1.6	Nd ³⁺ :YAG	V 6.2
microchannels	XI 6.2.2	near-edge X-ray absorption fine structure (NEXAFS)	VIII 2.4
micro-drilling	X 2.4	near scatter	IX 7.6.3
micrometer, μm	I Table App.	nebulization	III 3.1.1.1
microphone	XI 5.5.2	nebulizer	III 3.1.1.2; V 3.4.2;
microphotometer	I 8.2.3	nebulizer with heated spray chamber	III 3.1.1.2
microsample	V 6.8.2	needle valve	V 7.1
micro-surface removal	X 2.4	negative glow	V 7.1.1
micro-volumes	X 2.4	negative ion	V 2.1
microwave plasma	V 5.3	negative zone	V 7.1.1
middle slit	IX 2.1.1	net measure	III 4.1
Mie scattering	V 2.5.2	neutral	V 2.1
migration	V 2.1	neutral filter	IX 5.2
millings	X 2.1.2	noise	XI 4.3
minimal line width	I 5.2.2	noise equivalent power, F_N	XI 4.4
mist	III 3.1.1.1	non-coherent electromagnetic radiation	V 1
mode	V 6.1	non-coherent source	V 1
mode locking	V 6.1	non-conducting powder	V 3.4.2
modulation of linear polarized light	VI 3.4	non-current-carrying	V 3.1
molar concentration	VII 2.2	non-destructive analysis	X 2.4
molar (decadic) absorption coefficient	VII 2.2	non-destructive readout	XI 8.2.4.3
molecular band	V 3.6	non-diagram line	VIII 2.5
molecular radiation	V 2	non-homogeneous magnetic field	V 3.1.2
molecular spectra	V 2.2.2	non-homogeneous material	V 3.6
momentum transfer	V 7.1.3	non-linear optical techniques	XI 9.1
monochromatic radiation	IX 7.1	non-linearity error	VII 6.1
monochromator	I 5.1.1; 8.4.4; III 3.3; IX 2.1.1	non-periodic noise	XI 4.3
mortar	X 2.3.1	non-selective detector	XI 3
Mueller matrix	IX 7.5	non-selective quantum counter	XI 3

non-specific interference	III 4.4.2.2	outer zone	III 3.1.1.3
non-spectral interference	III 4.4.2.2	outlet	XIII 1.3
norm temperature	V 2.3.2	output signal	XI 3
normal eye (standard observer)	I 4.5	oven-dried	X 2.3.2
normal glow discharge	V 7.2.1	overcritically damped discharge	V 4.1.2
normal X-ray level	VIII 2.2	oxidant	III 3.1.1.3
normal X-ray line	VIII 2.5	oxidative acid digestion	X 3.2.1
normalized detectivity D^*	XI 4.4	oxygen-flask combustion	X 3.1.3
number of grating rulings			
per unit length, n_T	I 5.1.9	P	
number of grooves	IX 4.2.2	p- and n-type regions	XI 7.2.3
O		P-type delayed fluorescence	VI 2.1
observation volume	XII 1.1	PIN (p-intrinsic-n) diode	XI 7.2.3
observation zone	V 5.1.3	parallel ignition	V 4.3
off-plane Eagle mounting	IX 7.2.7	parallel configuration	V 6.1
one-dimensional detector	XI 8	paramagnetic compound	VI 2.2.4
one-step excitation source	V 6.6	partial digestion	X 3.2.2
on-off ratio	V 3.1.3	partial evaporation	V 3.4.2
open atomizer	XII 2.1.2	particle-induced X-ray	
open dynamic system	XIII 1.3	emission (PIXE)	VIII 2.1
open-ended hollow cathode	V 7.3.3	particle size	X 2.3.1
operating current	V 3	partitioned photocathode	XI 8.1.4
optical absorption	IX 2.2	parts per billion	I 6.2
optical beam	IX 4.2.1	parts per million	I 6.2
optical beam error	VII 6.6	Paschen-Runge	IX 9.2.6
optical conductance	IX 7.3.2	passage of flux	I 8.4.4
optical conductance, G	I 5.3.2; I 8.4.4	peak capacitor tension	V 4.1.1
optical filters	IX 5.2	peak diffraction coefficient	IV 5.1.3
optical fluorescence	IX 2.2	peak height absorbance	XII 2.3
optical multichannel analyzer	VII 3.3	peak-peak-method	VII 4.6
optical pumping	V 6.1	peak pulse power	V 6.1
optical radiation	IX 2	peak spark current	V 4.1.2
optical reflection	IX 2.2	peak wavelength	IX 7.4.1
optical scattering	IX 2.2	peak-zero-method	VII 4.6
optically thin plasma	V 7.3.4	pellet	V 3.4.2; X 3.1.1
optimal diameter	IX 7.2.5	X 3	
optimal entrance field stop	IX 7.2.6	X 3.1.1	
optimal field angle	IX 7.2.6	X 3.1.1	
optimal slit length	IX 7.2.5	V 7.1.2	
optimal slit width	IX 7.2.5	V 7.1.2	
optimum spark conditions	V 4.9	XI 4.3	
order of diffraction	IX 4.2.2	V 6.1	
order of interference	IX 4.2.3	VI 4.5	
order of the spectrum	I 5.1.9	XIII 1.2	
order overlap	IX 4.2.2	VI 2.1; Table	
order selector	IX 6	2.1	
order sorter	IX 6	VI 4.8	
organic effect	III 4.4.2.2	VI 3.4	
orifice	V 3.1.2	XI 7.2.6	
origin of characteristic		XI 7.2.7	
X-ray photons	IV 1.3	VIII 2.4	
oscillating spark	V 4.1.2	XI 3; XI 5.5.2	
oscillator	V 5.1.1	VII 1	
oscillator strength	V 2.3.5	XI 6	
outer flow	V 5.1.2; XII	XI 3	
	2.1.2	X 3.2.5	
outer gas	V 5.1.2	XI 7	

photoconductive mode	XI 7.2.1	polychromator	I 5.1.1; III 3.3; VII 3.3;
photocurrent	III 3.4		IX 2.1.2
photodetector	III 3.4	polycrystalline electrographite	XII 2.1.3
photodiode	XI 7.2.1	polycrystalline matrix	VII 2.1
photodiode array	XI 8.1.1	population inversion	V 6.1
photo-electric detector	XI 3	porous cup electrode (porode)	V 3.4.3
photo-emissive detector	XI 6	position-sensitive	
photographic parameter, <i>P</i>	I 8.3.1	photomultiplier tubes	XI 8.1.4
photometry	I 4.5	position-sensitive	
photomultiplier tube	III 3.4; VI 3.3; XI 6.2	proportional counters	XI 8.1.5
photon emission yield		positive column	V 7.1.1
(flourescence yield), <i>w</i>	IV 4.3.1	positive column current density	V 7.3.1
photon flux	XI 2	positive ion	V 2.1
photon irradiance	XI 2	postdisperser	IX 6
photons	XI 2	post-filter effect	VI 5.2
photothermal beam deflection	XI 9.4	potential gradient	V 7.1.2
phototransistor	XI 7.2.5	potential wells	XI 8.2.4.1
photovoltaic cell	III 3.4	powder technique	V 4.9
photovoltaic mode	XI 7.2.1	power amplification	V 5.1.1
physical equilibrium	III 6.1	power of detection	V 4.8
physical interference	III 4.4.2.2	power spectrum	XI 4.3
physical line profile function	IX 7.3.5	practical effective spectral	
physical line shape	V 2.4	FWHM	IX 7.2
pierce	V 5.1.2	practical resolution	IX 7.2.3
piezo-electric device	XI 5.5.2	practical resolution, <i>R</i>	I 5.2.2
pinch effect	V 3.1.2	practical instrumental finesse	IX 4.2.3
pipe samples	X 2.3.1	practical resolving power	IX 7.2.4
piston electrode	V 3.4.3	pre-arc	I 7.6.4
pixels (picture elements)	XI 8	precision	II 2.6; III 4.3.2
planar diffused diode	XI 7.2.3	preconcentration	X 3.3
Planck's law	V 2.2.3	predisperser	IX 6
plane cathode		pre-filter effect	VI 5.2
glow-discharge source	V 7.3.4	preheated platform	XII 2.2.2
plane grating	IX 4.2.2	preheated probe	XII 2.2.2
plane grating mountings	IX 9.3	premix burner	III 3.1.1.3
plane polarization	V 2.5.1	pre-spark	I 7.6.4
plasma	V 2; 2.3.1	prespark curve	V 4.9
plasma impedance	V 5.1.1	prespark period	V 4.9
plasma jet	V 3.2; III 3.1.3.2	pressed-disc	X 3.1.1
plasma parameter	V 5.1.3	pressure-sensitive detector	XI 5.5
plasma plume	V 3.2	pressure-tension-current	
plasma torch	V 5.1	relationship	V 7.1
plasmon excitation	VIII 2.5	primary-combustion zone	III 3.1.1.3
platform	XII 2.1.4	primary discharge	V 7.3.3
pneumatic detector	XI 5.5.1	primary excitation	VIII 2.1
pneumatic nebulizer	III 3.1.1.1; 3.1.1.2	primary radiation	IV 4.3
Pockels cell	V 6.2.3	primary source	V 2
point-to-plane	V 4.9	principal gas	V 4.6
point-to-point	V 4.9	prism	IX 2.1
polarity	V 3.4.1	prism angle	IX 4.2.1
polarization effect	XI 4.2	prism height	IX 4.2.1
polarization error	VII 6.5	prism mountings	IX 9.1
polarization state	IX 7.5	probe	XII 2.1.4
polarized radiation	V 2.5.1	projector screen	V 4.5
polyatomic gas	V 7	proportional counter	XI 6.4
		proportional	
		gas-scintillation counter	XI 6.4.3

protective agent	III 4.4.3	radiant energy, Q	I 6.3.1; XI 2
protective gas	XII 2.1.1	radiant exposure, H	IX 8.3.3; I 8.2.2; XI 2
proton energy	IV 4.2	radiant intensity	V 6
pulse amplitude	IV 5.1.5	radiant particle	V 3.6
pulse duration	V 6.1	radiant power	IX 7.3.3; V 6; XI 2
pulse energy	V 6.1	radiation detector	VII 3; XI 2
pulsed-discharge lamp	III 3.1.3.3.3	radiation input	XI 2; XI 4.1
pulsed laser source	V 6.1	radiation-less transition	VIII 2.1; VI 2.2.2
pulverizer	X 2.3.1	radiation noise	XI 4.3
pumped (systems)	V 7.1	radiation source	V 1; VII 3
pumping cavity	V 6.2	radiation through a cone	I 8.4.4
pumping lamp	V 6.2	radiative absorption	V 2.3.5
pumping period	V 6.1	radiative Auger effect	VIII 2.5
pump power	V 6.2.1	radiative de-excitation	V 2.3.5
purge gase	XIII 1.1	radiative equilibrium	III 6.1
pyro-electric detector	VI 3.3; XI 5.4	radiative process	V 2.3.5
pyro-electric photodetector array	XI 8.1.2	radiative recombination	V 2.2.3
pyrolysis curve	XII 2.2.3	radiative transition	VI 2.2.3
pyrolysis stage	XII 2.2.1	radiofrequency plasma (rf plasma)	V 5
pyrolysis temperature	XII 2.2.1	Raman scattering	VI 4.8
pyrolysis time	XII 2.2.1	ramp heating	XII 2.2.1
pyrolytic graphite	XII 2.1.3	random error	VII 5.1
pyrolytic graphite coating	XII 2.1.3	random fluctuation	VII 5.1
pyrolytic techniques	X 3.2.6	rate of liquid aspiration	III 3.1.2
Q		rate of liquid consumption	III 3.1.2
Q (quality factor)	V 6.2.3	Rayleigh scattering	V 2.5.2
quadratic electro-optical effect	V 6.2.3	reactant	XIII 1.1
quality characteristic	X 2.3.1	reading	III 3.5
quanta	XI 2	reagents	X 2.3.1
quantity	III 4.1; I 6.2.1; 8.4.4; II 2.1	recharging current	XI 8.2.2
quantum counter	VI 3.3	reciprocal linear dispersion	IX 4.3
quantum efficiency, $h(I)$	XI 4.2	recombination fluorescence	VI 2.1
quantum efficiency	XI 3	recovery test	III 4.3.2
quantum efficiency of luminescence	VI 4.6; Table 4.1	rectified ac arc	V 3.1.1
quantum yield of a photochemical reaction	VI 4.6	rectified source	V 3.5.1
quantum yield of fluorescence (phosphorescence)	VI 4.6; Table 4.1	reference beam	III 3.3
quench gas	IV 5.1.5	reference cell	VII 3.2.1
quenched fluorescence analysis	VI 2.2.2	reference element	V 5.4; I 6.2.2; 6.3.1; 8.4.4; III 4.4.3
quenching	V 2.3.4; III 5.1.3; X 2.1.2	reference-element technique	III 4.4.3
quenching gas	XI 6.4	reference intensity	I 8.4.4
quenched fluorescence analysis	VI 2.2.2	reference material	V 5.4
quenching	V 2.3.4; III 5.1.3; X 2.1.2	reference solution	V 5.4; III 5.1; VII 4.2
quenching gas	XI 6.4	reflected power	V 5.1.1
quenching processes	VI 4.6	reflection factor	IX 4.2; I 5.3.1
Q-switch	V 6.2.3	reflectivity finesse	IX 4.2.3
Q-switched operation	V 6.2.3	reflux nebulizer	III 3.1.1.2
R		refraction effect	VI 5.3
radiance or radiant intensity	I 6.3.1	refractive edge	IX 4.2.1
radiance temperature	V 2.3.2	refractive index	IX 4.2.1; I 5.2.1
radiant	I 4.5	refractor plate	IX 10

reignition tension	V 4.1.2	Rowland circle mounting	IX 9.2.6
relative aperture	IX 4.1	Rowland ghosts	IX 7.6.1
relative responsivity	XI 4.1	ruled plane grating	IX 4.2.2
relative spectral responsivity	XI 4.1	ruled grating	IX 4.2.2
relative standard deviation	III 4.3.2	ruling engine	IX 4.2.2
relative standard deviation, s_n	II 2.4	Rydberg series	VIII 2.2
release time	XIII 1.2		
releaser	III 4.4.3	S	
removal	XII 2.2.3	sample	I 6.1; III 4.1
repetition rate	V 6.1	sample beam	III 3.3
replica grating	IX 4.2.2	sample cell	VII 3.2.1
representative samples	X 2.4	sample cell holder	VII 3.2.1
residence time	V 5.1.2; XII 2.3	sample compartment	VII 3
residual (gas)	V 7.3.4	sample deposition temperature	XII 2.2.1
residual ionization	V 7.1.2	sample deposition time	XII 2.2.1
resistance-heated device	III 3.1.3.3.1	sample electrode	V 3.4.1
		sample error	VII 6.10
resistance-strip		sample injector	XII 2.1.4
magnetic photomultiplier	XI 6.2.1	sample introduction hole	XII 2.1.2
resistively heated atomizer	XII 1.1	sample introduction system	V 5.4
resistor	V 4.1.2	sample path length, b	I Table App.
resolution of Si(Li) detectors	IV 5.2.2	sample solution	V 5.4; X 3.2
resolved lines	IX 7.2.1	sample support	XII 2.1.4
resolved wavelength distance	IX 7.2.1	sample unit	X Figure 2
resolving power	IX 7.2.4	sampling boat	III 3.1.3.1
resolving power, R_0	I 5.2.2	sampling cup	III 3.1.3.1
resonance broadening	V 2.4.4	sampling loop	III 3.1.3.1
resonance emission	VIII 2.5	sampling plan	X 1.1
resonance fluorescence	III 5.1.3	sampling procedures	X 1
resonance line	VIII 2.5; III 5.1.1	sampling source	V 2
		satellites	IX 7.6.3
resonance spectrometer	III 3.3	saturable dye-switch	V 6.2.3
response time	III 3.5	saturation effect	VII 2.2
response time, t_R	XI 4.6	saturation (plateau)	III 4.4.3
responsivity	III 3.4	saturator	III 4.4.3
responsivity R	XI 4.1	sawings	X 2.1.2
restricted abnormal glow		saw-tooth shaped grooves	IX 4.2.2
discharge	V 7.2.2	scale expansion	III 3.5
restricted glow discharge	V 7.2.2	scanning finesse	IX 4.2.3
restrictor plate	V 7.3.4	scanning laser analysis	V 6.8.3
resultant spectral slit width	IX 7.1.3	scatter	IX 7.6; V 2.5.2; III 4.3.1
reversal dip	III 5.1.2	scattering	III 5.1.2
reversed direct-injection burner	III 3.1.1.3	scattering error	VII 6.7
rifflers	X 2.3.1	Schottky photodiode	XI 7.2.2
rise time, t_r	XI 4.6	scintillation counter	XI 6.2.3
Robin mounting	IX 9.2.3	scintillation detectors	IV 5.1.5
rocking curve	IV 5.1.3	scintillator	XI 6.2.3
rod atomizer	XII 2.1.2	screened-off	V 7.3.1
rod samples	X 2.1.1	sealed hollow cathode lamp	V 7.3.3
rolling	X 2.1.2	sealed lamp	III 3.2
rotating disc	V 6.2.3	second Rayleigh criterion	IX 7.2.1
rotating disc electrode (rotrode)	V 3.4.3	secondary atomization surface	XII 2.1.4
rotating mirror	V 6.2.3	secondary-combustion zone	III 3.1.1.3
rotating platform (platrode)	V 3.4.3	secondary discharge	V 7.3.3
rotating prism	V 6.2.3	secondary electron multiplication	XI 6.2
rotational transitions	V 2.2.2	secondary excitation	VIII 2.1
rotational temperature	V 2.3.2	secondary fluorescence	IV 4.3.4

secondary ionization	VIII 2.2	simultaneous spectrometer	IX 3.3.2
secondary radiation	IV 4.3	single-beam spectrometer	VI 3.2
seeded arc	V 3.6	single-beam system	III 3.3
selection rules	VIII 2.3	single-electrode plasma	III 3.1.3.2
selective detector	XI 3	single-element lamp	III 3.2
selective digestion	X 3.2.2	single pulse	V 6.2.3
selective micro-sample	X 2.4	single spark	V 4.1.2
selective volatilization	V 2.1; X 3.2.1	single wire (PSPC)	XI 8.1.5
self-absorption	VIII 2.4; III 5.1.2; I 7.6.2	singlet-singlet absorption	VI 2.2.1
self-absorption broadening	V 2.4.5	singlet-triplet absorption	VI 2.2.1
self-absorption effect	VI 5.2	sintering	X 3.2.1
self-electrode	V 3.4.1; X 2.1.1	sinusoidal function	I 8.4.4
self-ignited spark discharge	V 4.2	slab line cavities	V 5.3.2
self-reversal	V 2.4.6; III 5.1.2; I 7.6.3	sliding spark	V 4.7
self-conducting surface	V 7.2.3	slit	I 5.1.2
semi-Q-switched	V 6.2.3	slit width, s	I 5.1.2
semiconductor bolometer	XI 5.3	slot burner	III 3.1.1.3
semiconductor detector	XI 7	slow wave structures	V 5.3.2
sensing area	XI 8	solar blind detectors	XI 6.1
sensitive area, A	XI 4.7.1	solid angle	V 6
sensitive volume, V	XI 4.7.2	solid-sample holder	VII 3.2.3
sensitivity	III 4.2; II 2.2; XI 4.1	solid state crystal lattice	V 7.1.3
sensitized luminescence	VI 2.2.2	solid-state detector	IV 5.2.1
separated flame	III 3.1.1.3	solubilization	X 3.2.3
separation	X 3.3	solute-volatilization interference	III 4.4.2.2
sequential spectrometer	IX 3.3.1	solution	I 6.1
series ignition	V 4.3	solvent	I 6.1
settling error	VII 6.1	solvent blank	III 3.5
settling time	XI 4.6	solvent effect	VI 5.4
Seya-Namioka mounting	IX 9.2.2	space charge	V 7.1.3
shape resonance	VIII 2.4	space-resolving technique	V 6.8
shatter-box mill	X 2.3.1	spark chamber	V 4.5
shattered	X 3.1.4	spark channel	V 4.1.2
shavings	X 2.1.2	spark cross-excitation	V 6.7.1
sheet-samples	X 2.1.1	spark duration	V 4
shield	V 7.3.1	spark energy	V 4.2
shielded electrical discharge	V 3.5.2	spark erosion	X 2.1.2
shielded flame	III 3.1.1.3	spark frequency	V 4.1.2
short-circuit discharge	V 7.3.4	spark gap	V 4
shot noise	XI 4.3	spark ignition	V 4
Shpol'skii spectrum	VI 2.2.4	spark pistol	X 2.1.1
shredding	X 2.3.2	sparklike discharge	V 4.3
side-on tube	XI 6.1	spark repetition rate	V 4.1.2
sievings	X 2.3.1	spark stand	V 4.5
sifter electrode	V 3.4.3	sparking equilibrium	V 4.9
silica tube atomizer	XII 1.1	sparks per half cycle	V 4.2
silicon doped with arsenide (Si:As)		spatial distribution interference	V 5.4; III 4.4.2.2
photoconductive detector	XI 7.1	spatial distribution of radiation	V 7.1.1
silicon photodiode	VI 3.3	spatial distribution	
silicon photodiode array	VII 3.3	(of the irradiance)	XI 8
silicon target	XI 8.2.2	spatial resolution	XI 8
silicon-intensified target vidicon		spatial stabilization	V 3.1.2
(SIT vidicon)	XI 8.2.3	spatially resolved measurements	XI 3
simulation technique	III 4.4.3	spatially resolving detectors	XI 8
		spear samples	X 2.3.1
		special terms	I 7.6
		speciation	X 3.2.2

specific (decadic)		spray discharge	V 7.2.3
absorption coefficient	VII 4.2	sprayer	III 3.1.1.1
specific discharge characteristic	V 7.2	spread time	XI 4.6
specific interference	III 4.4.2.2	sputtering	V 2.1; X 2.1.2
spectral apparatus	IX 2; VII 3	sputtering rate	V 7.1.3
spectral background absorbance	VII 4.3	sputtering yield	V 7.1.3
spectral band	IX 2; III 5.1.1	stabilization ring	V 3.1.2
spectral band selection	IX 10	stabilized arc	V 3.1
spectral bandwidth error	VII 6.3	stabilized current supply	V 3.5.1
spectral continuum	III 5.1.1; IV 4.1.3	stabilizer temperature	
(spectral) continuum source	III 3.2	atomization	XII 2.2.2
spectral distribution	VII 3.1	stabilized tension supply	V 3.5.1
spectral filters	IX 2.2	standard deviation	III 4.3.1
spectral instrument	IX 2	standard deviation, s	II 2.3
spectral interference	III 4.4.2.1	standard deviation for counting	IV 6.2
spectral irradiance	XI 2	Stark broadening	V 2.4.4
spectral line	VIII 2.5; III 5.1.1	Stark shift	V 2.4.4
spectral lines	I 7.6.1	static system	XIII 1.3
spectral line source	IX 7.3.5; III 3.2; VII 3.1	stationary radiation conditions	V 3.4.3
(spectral) luminous efficiency	I 4.5	steady state	V 5.4
spectral optical conductance		step sector	I 8.4.2
of a monochromator	IX 7.3.4	stepwise heating	XII 2.2.1
spectral power	XI 2	stepwise line fluorescence	III 5.1.3
spectral purity	X 7.1	Stern-Volmer law	VI 4.6
spectral radiance	V 7.3.1; I 4.2; VII 3.1	stigmatic arrangement	IX 2
spectral radiance		stimulated emission	V 2.3.5
of the black body, B_I^b	I 4.4	Stokes fluorescence	III 5.1.3
spectral radiant energy	XI 2	Stokes type	VI 2.2.3
spectral radiant energy density	V 2.3.5	Stokes vector	IX 7.5
spectral radiant exposure	XI 2	stopped flow	XII 2.1.2
spectral radiation quantities	I 4.3	stopped-flow cell	VII 3.2.4
spectral response curve	III 3.4	storage arrays	XI 8.2.4.1
spectral responsivity, $s(I)$	XI 4.1	straight slits	IX 4.1
spectral responsivity function	XI 4.1	stray light	I 6.3.5
spectrochemical buffer	III 4.4.3; I 7.7.2; X 3.1.2	stray radiation	IX 7.1.2; VII 6.4
spectrochemical carrier	I 7.7.5; X 3.1.2	stray-radiation error	VII 6.4
spectrograph	IX 3.2; I 5.1; Table App.	stray radiation factor	IX 7.1
spectrometer	IX 3.3; I 5.1.1; Table App., III 3.3; Table 1.1	streak camera	XI 9.3
spectrometer resolution	IV 5.1.4	streak tube	XI 9.3
spectrometry	III Table 1.1	striations	V 7.1.1
spectrophotometer	I Table App.	strike initiate	V 7.3.1
spectroscope	IX 3.1	strip atomizer	XII 2.1.2
spectroscopic terms, T	I 7.4	strip dynode photomultiplier	
sphere of radius, r	I 8.4.4	tube	XI 6.2.1
spike peak power	V 6.2.2	sub-sampling	X 2.3.1
spin conservation rule	VI 2.2	sublimation	V 2.1
spin doublet	III 2.2	subtractive double	
splash samples	X 2.1.1	monochromator	IX 2.1.1
spray chamber	III 3.1.1.2	suction nebulizer	III 3.1.1.2
		super-position	V 6.8.3
		superconductor bolometer	XI 5.3
		supplementary discharge	V 7.3.3
		supplementary electrode	V 7.3.3
		supplementary source	V 6.7
		supply	XII 2.2.3
		supply disc	V 3.4.3
		support	V 6.8.2

suppressor	III 4.4.3	thermopile	VI 3.3; XI 5.2
suprathermal chemiluminescence	III 5.1.1	thinned charge-coupled devices (thinned CCDs)	XI 8.2.4.2
surface analysis	X 2.4	three-electrode plasma	V 3.3
surface defects finesse	IX 4.2.3	three-slot burner	III 3.1.1.3
surface spark	V 4.7	thyristor control	V 3.5.1
surface wave		tilt of the plate, q	I 5.1.6
propagation structures	V 5.3.2	time constant, t_c	III 3.5; XI 4.6
Sustain a discharge	V 7	time gating	XI 4.6
synchronously excited spectrum	VI 4.4	time-integrated measurements	XI 3
synchronously rotating gap	V 4.2	time-integrating photodiode arrays	XI 8.2.1
synchrotron radiation	VIII 2.1	time integrating spatially resolving detectors	XI 8
T		time-of-wait curve	V 4.9
T-tubes	III 3.1.3.1	time-resolved measurements	XI 3
tail flame	V 5.1	time-resolved spectroscopy	V 4.8; I 7.6.4
tandem gap	V 4.2	time-resolving technique	V 6.8
tangent method	VII 4.6	time spread	XI 6.2
tantalum carbide-coated tube	XII 2.1.3	tissue-blender	X 2.3.2
tapered rectangular cavity	V 5.3.2	total angle of deviation	IX 4.2
target	V 6; XI 8.2.2	total decomposition	X 3.2.2
temperature coefficient		total number of rulings, N	I 5.1.9
of responsivity	XI 4.8	total transmittance	VII 2.2
temperature coefficient		Townsend first coefficient	V 7.1.2
of resistance	XI 5.3	transferred plasma	V 3.3
temperature effect	VI 5.4	transient pressure oscillation	XI 5.5.2
temperature error	VII 5.2	transit time	V 5.1.2
temperature noise	XI 4.3	transit time (of charge carriers)	XI 4.6
temperature profile	XII 2.2.3	transition probability for absorption	V 2.3.5
temperature programme	XII 2.2.1	transition probability for spontaneous emission	V 2.3.5
temporal spacing	V 6.1	transition probability for stimulated emission	V 2.3.5
temporal stabilization	V 3.1.2	transmission factor	IX 4.2; I 5.3.1
tension-current characteristics	V 3.1.1	transmittance, T	I Table App.
tension-time relationship	V 3.1	transmittance, T_p	I 8.2.3
term	VIII 2.2	transport interference	III 4.4.2.2
Tesla coil	V 3.5.1	transportation (process)	V 2.1
test sample	X 2.3.1	transversal mode	V 6.1
theoretical effective spectral FWHM	IX 8.1	transverse electromagnetic mode TM ₀₁₀ cavities	V 5.3.2
theoretical finesse	IX 4.2.3	trapping (adsorbing)	V 7.1.4
theoretical resolution	IX 7.2.2	triggerable stationary gap	V 4.2
theoretical resolving power	IX 4.2	trioxide (layers)	V 7.3.1
thermal detector	XI 3	triplet-triplet absorption	VI 2.2.1
thermal equilibrium	V 2.3.2; III 6.1	tube-in-tube atomizer	XII 2.1.4
thermal evaporation	V 4.9	tunable laser	VII 3.2
thermal noise	XI 4.3	tuned amplifier measuring system	V 7.3.4
thermal processes	V 7.3.1	tuned-line oscillator	V 5.1.1
thermal radiation	V 2.3.2; III 5.1.1	tungsten-filament lamp	III 3.2
thermal treatment	XII 2.2.1	tungsten-halogen lamp	V 6.2.1; VII 3.1
thermally ignited arc	V 3.1.1	tungsten probe atomizer	XII 2.1.4
thermally insulated cell	VII 3.2.4	tungsten strip	XII 2.1.3
thermistor bolometer	XI 5.3	turbulent (flame)	III 3.1.1.3
thermochemical reaction	V 3.4.2	turnings	X 2.1.2
thermocouple	XI 5.1		
thermodynamic equilibrium	V 2.3.2; III 6.1		
thermodynamic temperature	V 2.3.2; III 6.1; Table 2.1		
thermo-electric effect	XI 5.1		

twin nebulizer	III 3.1.1.2	vidicon	XI 8.2.2
two-dimensional array CCD	XI 8.2.4.1	vidicon tube	VII 3.3
two-dimensional detector	XI 8	virtual diffraction pattern	IX 7.2.5
two-dimensional photodiode array	XI 8.1.1	visible light photons (in a scintillation counter)	XI 6.2.3
two-step atomization-excitation procedure	V 6.7	visible region	I Table App.
Twyman interferometer	IX 5.3	volatilization	V 2; III 3.1.1.1
types of detectors	XI 3	volatilization rate	V 2.1
		volatilizer	I 7.7.4; III 4.4.3; X 3.1.2
U		W	
ultimate focal spot diameter	V 6.4	Wadsworth mounting	IX 9.2.1
ultrasonic nebulizer	III 3.1.1.2	Wadsworth prism mounting	IX 9.1.2
ultraviolet region	I Table App.	wall	XII 2.1.4
uncontrolled ac arc	V 3.1.1	wall atomization	XII 2.1.4
uncontrolled high tension spark generator	V 4.2	wall-stabilized arc	V 3.1.2
undercritically damped oscillating discharge	V 4.3	wall temperature	XII 2.2.2
unenclosed atomizer	XII 2.1.1	waveguide	V 5.3
unidirectional discharge	V 4.1.2	wavelength, <i>l</i>	I Table App.
unresolvable band spectra	V 2.2.3	wavelength converter	XI 9.1
upconversion		wavelength dispersion	IV 5.1
(wavelength converter)	XI 9.1	wavelength error	VII 6.2
upper wavelength limits	IX 4.2	wavelength modulation	VI 3.4; VII 3
uptake rate	V 5.1.3	wavelength modulation interval	VII 4.6
usable free spectral range	IX 4.2.2	wavelength shift	VII 7
usable wavelength-range	VII 3.1	wavenumber, <i>n</i>	I Table App.
useful spectral range	XI 4.1	weak potential gradient	V 7.1
UV/VIS absorption spectrum	VII 2.1	weighted mean wavelength	IX 7.4.3
		wet grinding	X 2.3.1
V		wet-matter	X 2.3.2
vacuum-coating	X 2.1.2	white noise	XI 4.3
vacuum cup electrode	V 3.4.3	width of the line	I 5.2.2
vacuum-deposition	X 2.1.2	width (spectral line)	V 2.2.3
vacuum-dried	X 2.3.2	window-less detector	XI 6.1
vacuum-melt	X 2.1.2	wire atomizer	XII 2.1.2
vacuum phototube	III 3.4; XI 6.1	wire samples	X 2.1.1
vacuum spark	V 4.7	work function	V 7.3.1
valence levels	VIII 2.2	working gas	V 4.5
vaporization temperature	XII 2.2.3	X	
vapour cloud	V 4.1.2	xenon arc lamp	VII 3.1
vapour generation		X-ray fluorescence	IV 4.3
with analyte collection	XIII 1.2	X-ray generation by positive ions	IV 4.2
vapour jet	V 4.1.2	X-ray levels	VIII 2.2
vapour-phase interference	III 4.4.2.2	X-ray satellites	VIII 2.5
variable filter	IX 5.2	Y	
variable-path length cell	VII 3.2.4	yield	IV 4.1.2
variance	II 2.5; III 4.3.1	Z	
venetial blind structure (of a dynode chain)	XI 6.2	Zeeman effect	V 2.4.7
vibrational temperature	V 2.3.2	zero bias (of a photodiode)	XI 7.2.1
vibrational transitions	V 2.2.2	zero suppression	III 3.5
vibronic transition	VII 2.1		